AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

LISTING OF CLAIMS:

- 1. (currently amended) A vinyl ether curing composition, comprising:
- a polyfunctional vinyl ether compound, the polyfunctional vinyl ether compound being free from carbonyl groups and hydroxyl groups;
 - a polyhydric phenol compound; and
 - a flame retardant,

wherein the composition contains 10 to 30 parts by weight of a phosphorus-based flame retardant as the flame retardant per 100 parts by weight of the total of the polyfunctional vinyl ether compound and the polyhydric phenol compound.

2. (currently amended) The vinyl ether curing composition according to claim 1, comprising 100 parts by weight of the polyfunctional vinyl ether compound, wherein the composition contains 30 to 200 parts by weight of the polyhydric phenol compound, 10 to 3000 parts by weight of a filler, and 10 to 200 parts by weight of a flame retardant per 100 parts per weight of the polyfunctional vinyl ether compound.

- 3. (previously presented) The vinyl ether curing composition according to claim 1, wherein the polyfunctional vinyl ether compound is a tetra- or higher functional vinyl ether compound.
- 4. (previously presented) The vinyl ether curing composition according to claim 1, wherein the polyhydric phenol compound is a phenol resin represented by general formula (I):

$$(I) \qquad \qquad (I)$$

wherein n represents 0 or 1; and m represents a number of from 1 to 10000.

- 5. (previously presented) The vinyl ether curing composition according to claim 1, containing 10 to 1000 parts by weight of silica as the filler per 100 parts by weight of the total of the polyfunctional vinyl ether compound and the polyhydric phenol compound.
 - 6. (canceled)

7. (previously presented) The vinyl ether curing composition according to claim 1, wherein the phosphorus-based flame retardant is a compound represented by formula (II):

$$(II)$$

- 8. (previously presented) The vinyl ether curing composition according to claim 1, further comprising a polyepoxy compound.
- 9. (previously presented) A prepreg formed by using the vinyl ether curing composition according to claim 1.
- 10. (previously presented) The vinyl ether curing composition according to claim 2, wherein the polyfunctional vinyl ether compound is a tetra- or higher functional vinyl ether compound.

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11. (previously presented) The vinyl ether curing composition according to claim 2, wherein the polyhydric phenol compound is a phenol resin represented by general formula (I):

$$\begin{array}{c|c} OH & OH \\ \hline C_{H_2} & \\ \hline \end{array} \begin{array}{c} OH \\ \end{array} \begin{array}{c} OH \\ \end{array} \end{array} \begin{array}{c} OH \\ \end{array} \begin{array}{c} OH \\ \end{array} \end{array} \begin{array}{c} OH \\ \end{array} \begin{array}{c} OH \\ \end{array} \begin{array}{c} OH \\ \end{array} \end{array} \begin{array}{c} OH \\ \end{array} \begin{array}{c} OH \\ \end{array} \end{array} \begin{array}{c} OH \\ \end{array} \begin{array}{c} OH \\ \end{array} \begin{array}{c} OH \\ \end{array} \begin{array}{c} OH \\ \end{array} \end{array} \begin{array}{c} OH \\ \end{array} \begin{array}{c} OH \\ \end{array} \begin{array}{c} OH \\ \end{array} \end{array} \begin{array}{c} OH \\ \end{array} \begin{array}{c} OH \\ \end{array} \end{array} \begin{array}{c} OH \\ \end{array} \begin{array}{c} OH \\ \end{array} \begin{array}{c} OH \\ \end{array} \end{array} \begin{array}{c} OH \\ \end{array} \begin{array}{c} OH \\ \end{array} \begin{array}{c} OH \\ \end{array} \end{array} \begin{array}{c} OH \\ \end{array} \begin{array}{c} OH \\ \end{array} \end{array} \begin{array}{c} OH \\ \end{array} \begin{array}{c} OH \\ \end{array} \end{array} \begin{array}{c} OH \\ \end{array} \begin{array}{c} OH \\ \end{array} \begin{array}{c} OH \\ \end{array} \end{array} \begin{array}{c} OH \\ \end{array} \begin{array}{c} OH \\ \end{array} \end{array} \begin{array}{c} OH \\ \end{array} \begin{array}{c} OH$$

wherein n represents 0 or 1; and m represents a number of from 1 to 10000.

12. (previously presented) The vinyl ether curing composition according to claim 3, wherein the polyhydric phenol compound is a phenol resin represented by general formula (I):

$$\begin{array}{c|c} OH & OH \\ \hline \\ C \\ H_2 \end{array} \begin{array}{c} OH \\ \hline \\ H_2 \end{array} \begin{array}{c} OH \\ \hline \\ H_2 \end{array} \begin{array}{c} H \\ \hline \end{array}$$

wherein n represents 0 or 1; and m represents a number of from 1 to 10000.

- 13. (previously presented) The vinyl ether curing composition according to claim 2, containing 10 to 1000 parts by weight of silica as the filler per 100 parts by weight of the total of the polyfunctional vinyl ether compound and the polyhydric phenol compound.
- 14. (previously presented) The vinyl ether curing composition according to claim 3, containing 10 to 1000 parts by weight of silica as the filler per 100 parts by weight of the total of the polyfunctional vinyl ether compound and the polyhydric phenol compound.
- 15. (previously presented) The vinyl ether curing composition according to claim 4, containing 10 to 1000 parts by weight of silica as the filler per 100 parts by weight of the total of the polyfunctional vinyl ether compound and the polyhydric phenol compound.

16-19. (canceled)

20. (previously presented) The vinyl ether curing composition according to claim 2, wherein the phosphorus-based flame retardant is a compound represented by formula (II):

$$(II)$$